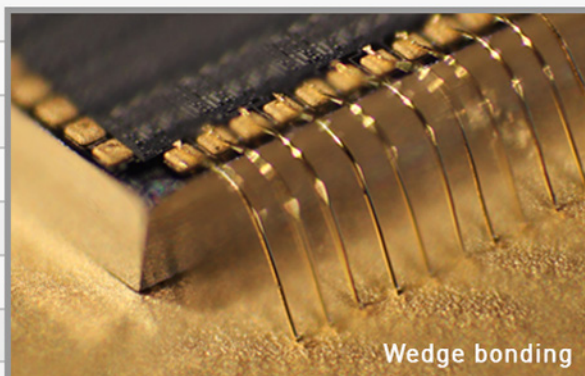
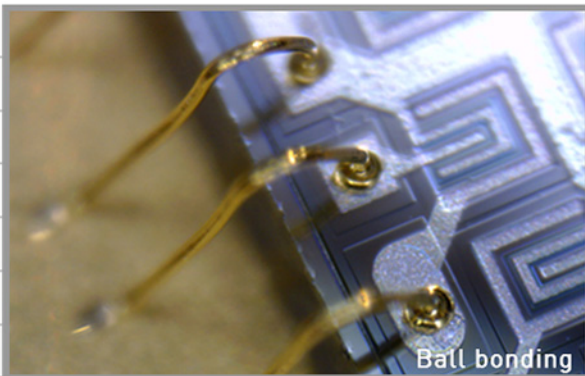




HB16 Wedge & Ball Bonder

Motorized Z- & Y- Axes



- + Wedge, Ball, Bump and Ribbon bonding
- + 17 μ to 75 μ Wire and 25 μ x 250 μ Ribbon
- + 6,5" TFT Touch Screen
- + Deep-Access Wedge 16mm / Ball 13mm
- + Bond Arm Length 165mm
- + 100 Program Storage Capacities
- + Motorized Z- & Y-Axis
- + Programmable Loop Profile
- + USB Backup
- + Electronic Ball Size Control
- + Pick & Place Option
- + Pull Tester Option
- + Copper Bonding Option

HB16 Thermosonic Wire Bonder for Wedge & Ball Bonding

The HB16 is a **Bench Top Size Wire Bonder**, ideal for laboratories, pilot and small scale production lines. **One Bond Head** for bonding in Ball/Wedge or Wedge/Wedge bonding mode. Only tool change necessary. Easy operation with **TFT Touch Screen** and direct access and simple adjustment of all bond parameters.

Technical Specifications

| | |
|-------------------------|---|
| Bonding Methode | Wedge-Wedge, Ball-Wedge, Ribbon- & Bumb- bonding |
| Gold wire diameter | 17 - 75 μm (0,7 - 3") |
| Aluminium wire diameter | 17 - 75 μm (0,7 - 3") |
| Ribbon size | max. 25 x 250 μm (1 x 9,8") |
| Ultrasonic system | 63,3 kHz Transducer PLL Control |
| Ultrasonic power | 0 - 10 Watt Output |
| Bond time | 0 - 20000 msec. |
| Bond force | 5 - 150 cN (350 cN option) |
| Bonding tool | 1,58 \varnothing 19mm length (0,0624" x 0,750") |
| Motorised Wire Spool | 50,8 mm (2") |
| Wire termination | Bond Head Tear / Clamp Tear |
| Wire feed angle | 90° |
| Clamp movement | Motorized, Up / Down |
| Ball size control | Electronic |
| Motorized Z travel | 17 mm (0,67") |
| Motorized Y travel | 10 mm (0,39") |
| Throat depth | 165 mm (6,5") |
| Fine Table motion | 10 mm (0,39") |
| Mouse ratio | 6:1 |
| Temperature controller | up to 250°C +/- 1°C |
| Electrical Requirements | 100 - 240V +/- 10% 50/60 Hz 10A max. |
| Physical Dimensions | 680 (27") x 640 (25") x 490 mm (19") |
| Weight | Net 42 kg |
| Industry Standards | CE standards |

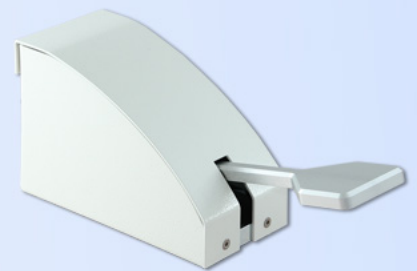
Accessories:



H26 Heater Stage with Pick & Place



H69 Bond Starter Kit



H51 Manual Z-Axis Control



H21 Heater Stage 100 x 100mm



H50 Spotlight Targeting System



H89 Video Targeting System

Specifications are subject to change without prior notice



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Made in Germany